

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Office of the Commissioner of Patents and Trademarks  
MAY 10 2004  
In re application of: Paul Robert Hoffman and David Albert Zoba  
Application No.: 10/771,072 Art Unit.: 2812  
Filing Date: 02/02/2004 Examiner: unknown  
For: "STRUCTURES FOR IMPROVING HEAT DISSIPATION IN STACKED SEMICONDUCTOR  
PACKAGES"

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Date: May 4, 2004

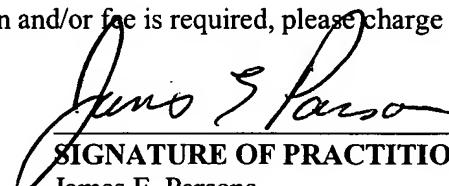
**SECOND PRELIMINARY AMENDMENT TRANSMITTAL**

1. Transmitted herewith is an amendment for this application.
2. STATUS: Applicant is other than a small entity.
3. EXTENSION OF TERM: The proceedings herein are for a patent application and the provisions of 37 C.F.R. 1.136 apply. Applicant believes that no extension of term is required. However, this conditional petition is being made to provide for the possibility that applicant has inadvertently overlooked the need for a petition for extension of time.
4. FEE FOR CLAIMS: The fee for claims (37 C.F.R. 1.16(b)-(d)) has been calculated as shown below:

(Col.1)	(Col. 2)	(Col. 3)	LARGE ENTITY		
Claims Remaining After Amendment	Highest No. Previously Paid For	Present Extra	Rate	Addit. Fee	
Total 24	Minus 25	= 0	x \$18 =	\$0	
Indep. 4	Minus 4	= 0	x \$86 =	\$0	
First Presentation of Multiple Dependent Claim			+ \$290 =	\$0	
			Total		
			Addit. Fee	\$0	

No additional fee for claims is required.

5. FEE DEFICIENCY: If any additional extension and/or fee is required, please charge Deposit Account No. 50-0574.



SIGNATURE OF PRACTITIONER  
James E. Parsons  
Reg. No. 34,691

Customer No. 022888  
Tel.: (408) 451-5906

I hereby certify that this correspondence is being deposited with the United States Postal Service as FIRST CLASS MAIL in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on May 4, 2004.

*5/4/2004* *Rebecca A. Baumann*  
Date Signature: Rebecca A. Baumann



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Applicants: Paul Robert Hoffman and David Albert Zoba

Assignee: Amkor Technology, Inc.

Title: Structures For Improving Heat Dissipation In  
Stacked Semiconductor Packages

Serial No.: 10/771,072 File Date: 02/02/2004

Examiner: Not Yet Assigned Art Unit: 2812

Docket No.: AMK-11317-1D

Date: May 4, 2004

Commissioner for Patents  
P.O. Box 1450  
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SECOND PRELIMINARY AMENDMENT

Dear Sir:

Please amend the application as follows.